SupIRBuck™

USER GUIDE FOR IRDC3473 EVALUATION BOARD

DESCRIPTION

The IR3473 SupIRBuck™ is an easy-to-use, fully integrated and highly efficient DC/DC voltage regulator. The onboard constant on time hysteretic controller and MOSFETs make IR3473 a space-efficient solution that delivers up to 6A of precisely controlled output voltage. IR3473 is housed in a 4mmx5mm QFN package.

Key features offered by IR3473 include: programmable switching frequency, soft start, temperature compensated over current protection, and thermal shutdown allowing a very flexible solution suitable for many different applications and an ideal choice for battery powered applications.

Additional features include pre-bias startup, a very precise 0.5V reference, forced continuous conduction mode option, over/under voltage protection, power good output, and enable input with voltage monitoring capability.

This user guide contains the schematic, bill of materials, and operating instructions of the IRDC3473 evaluation board. Detailed product specifications, application information and performance curves at different operating conditions are available in the IR3473 data sheet.

BOARD FEATURES

- V_{IN} = +12V
- V_{CC} = +5V
- V_{OUT} = +1.05V
- I_{OUT} = 0 to 6A
- F_S = 300kHz @ CCM
- L = 2.2µH
- C_{IN} = 22µF (ceramic 1210) + 68µF (electrolytic)
- C_{OUT} = 47µF (ceramic 0805) + 150µF (POSCAP)

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CONNECTIONS and OPERATING INSTRUCTIONS

An input supply in the range of 8 to 19V should be connected from VIN to PGND. A maximum load of 6A may be connected to V_{OUT} and PGND. The connection diagram is shown in Fig. 1, and the inputs and outputs of the board are listed in Table 1.

IRDC3473 has two input supplies, one for biasing (VCC) and the other for input voltage (VIN). Separate supplies should be applied to these inputs. VCC input should be a well regulated 4.5V to 5.5V supply connected to VCC and PGND. Enable (EN) is controlled by the first switch of SW1, and FCCM option can be selected by the second switch of SW1. Toggle the switch to the ON position (marked by a solid square) to enable switching or to select FCCM. The absolute maximum voltage of the external signal applied to EN (TP4) and FCCM is +8V.

Table 1. Connections

Connection	Signal Name
VIN (TP2)	VIN
PGND (TP5)	Ground for VIN
VCC (TP16)	VCC Input
PGND (TP17)	Ground for VCC Input
VOUT (TP7)	V_{OUT} (+1.05V)
PGND (TP10)	Ground for V_{OUT}
EN (TP4)	Enable Input

LAYOUT

The PCB is a 4-layer board. All layers are 1 oz. copper. IR3473 and other components are mounted on the top and bottom layers of the board.

The power supply decoupling capacitors, bootstrap capacitor and feedback components are located close to IR3473. To improve efficiency, the circuit board is designed to minimize the length of the on-board power ground current path.

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CONNECTION DIAGRAM

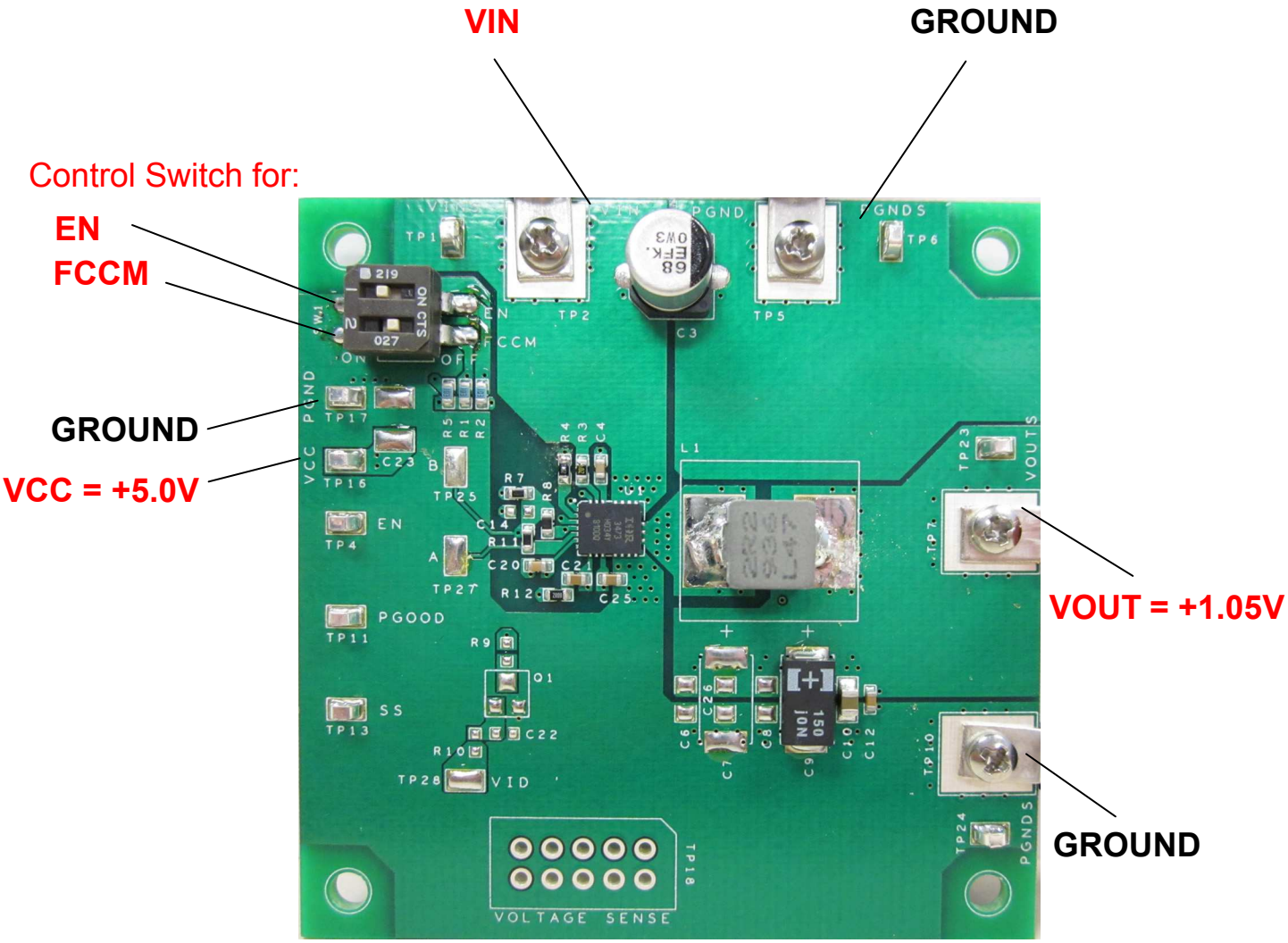

Fig. 1: Connection Diagram of IRDC3473 Evaluation Board

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PCB Board Layout

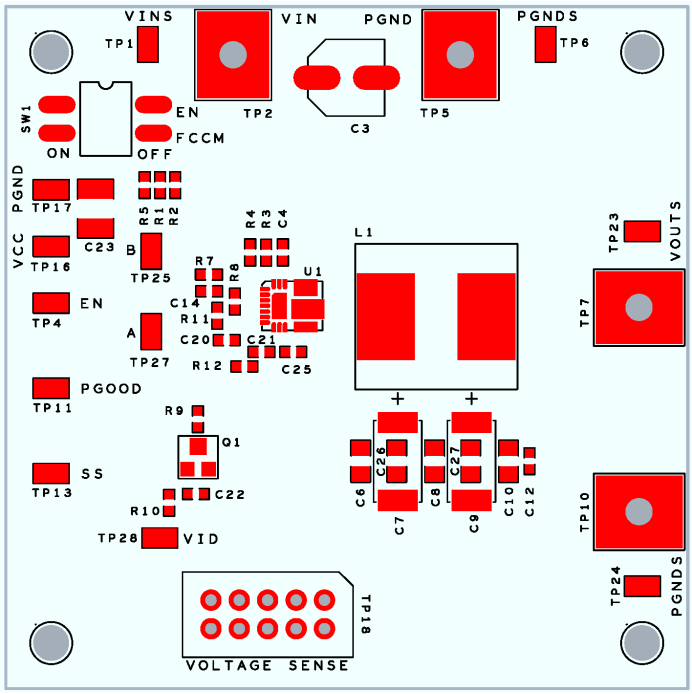

Fig. 2: Board Layout, Top Components

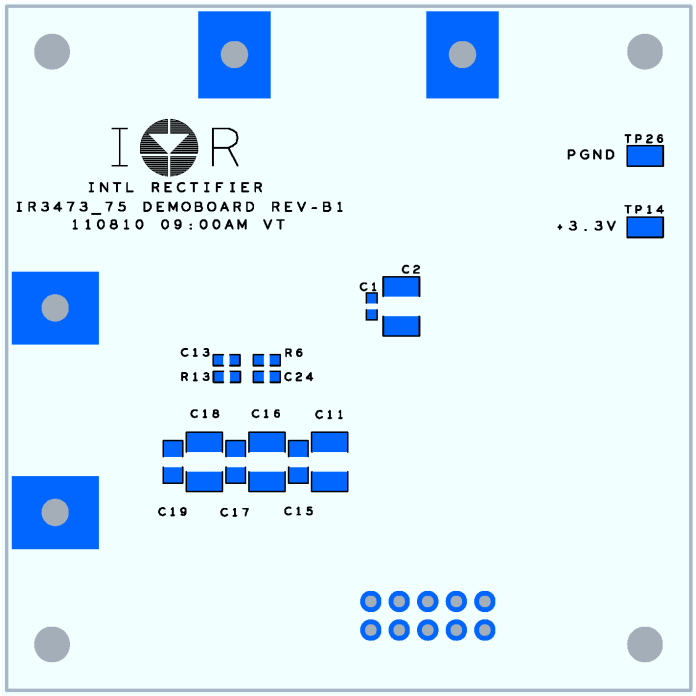

Fig. 3: Board Layout, Bottom Components

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PCB Board Layout

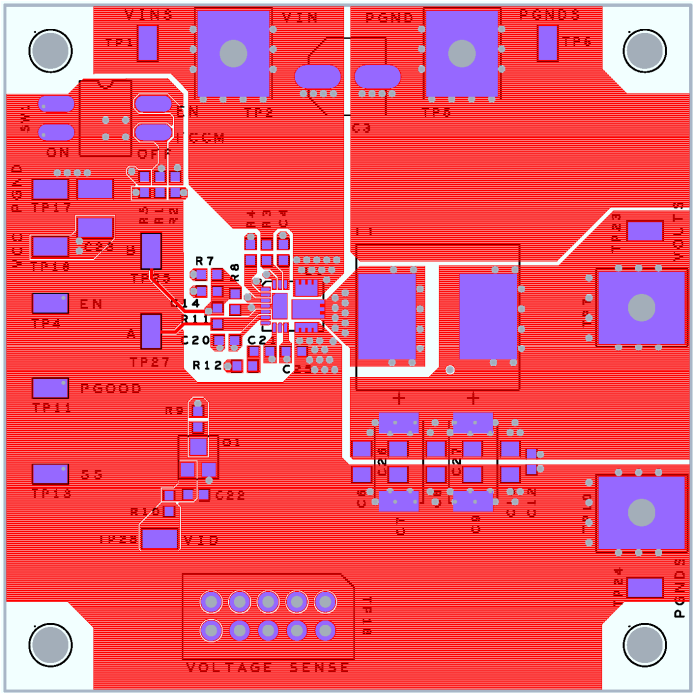

Fig. 4: Board Layout, Top Layer

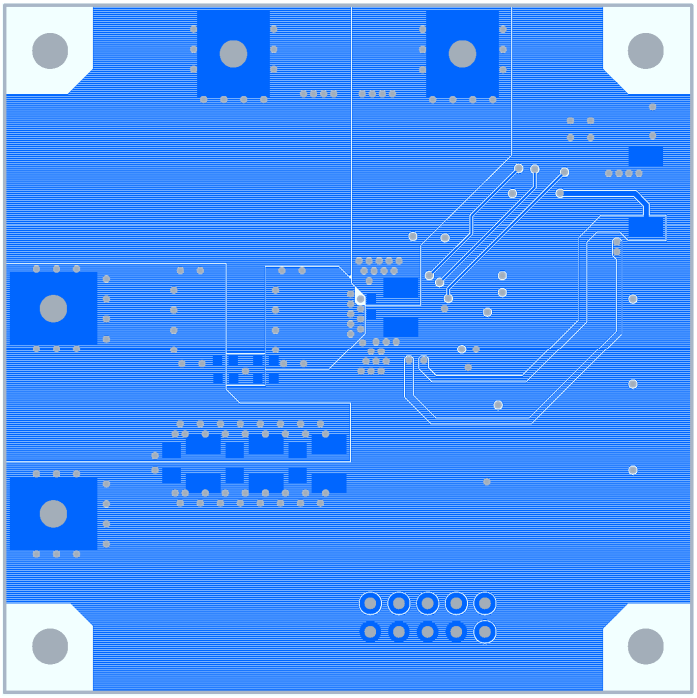

Fig. 5: Board Layout, Bottom Layer

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PCB Board Layout

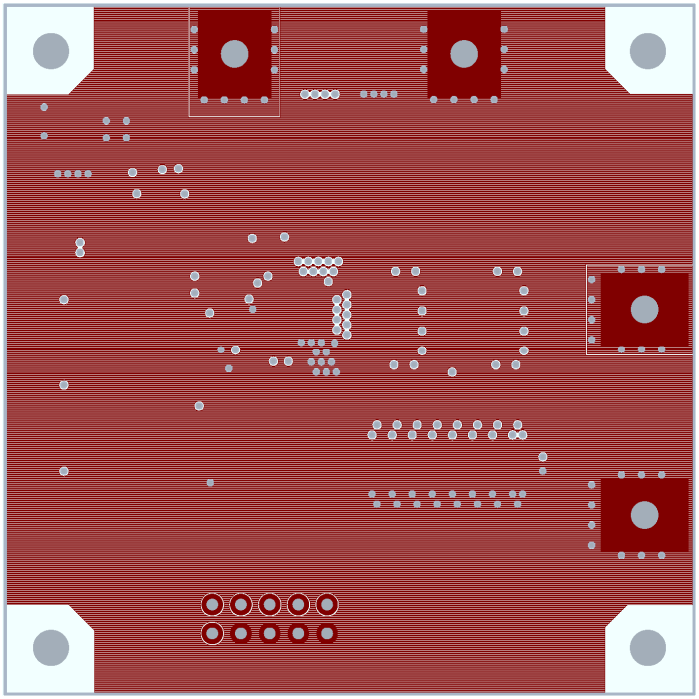

Fig. 6: Board Layout, Mid-layer I

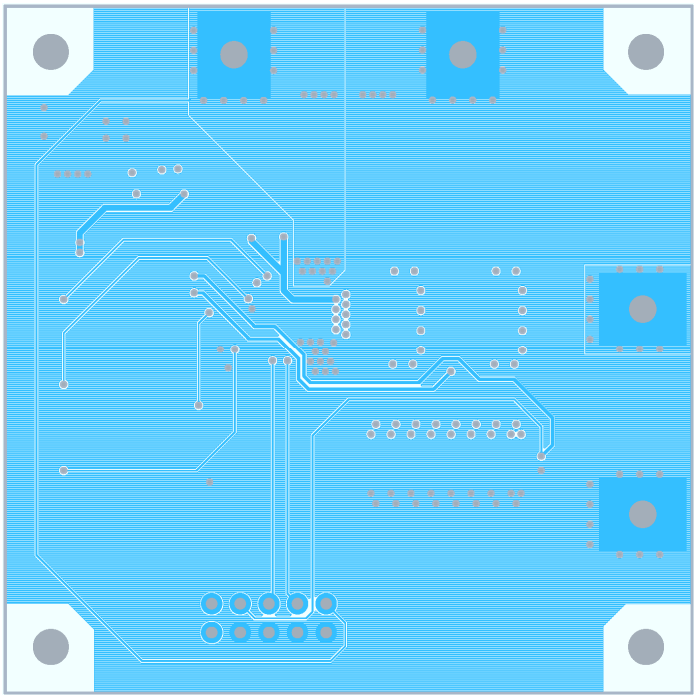

Fig. 7: Board Layout, Mid-layer II

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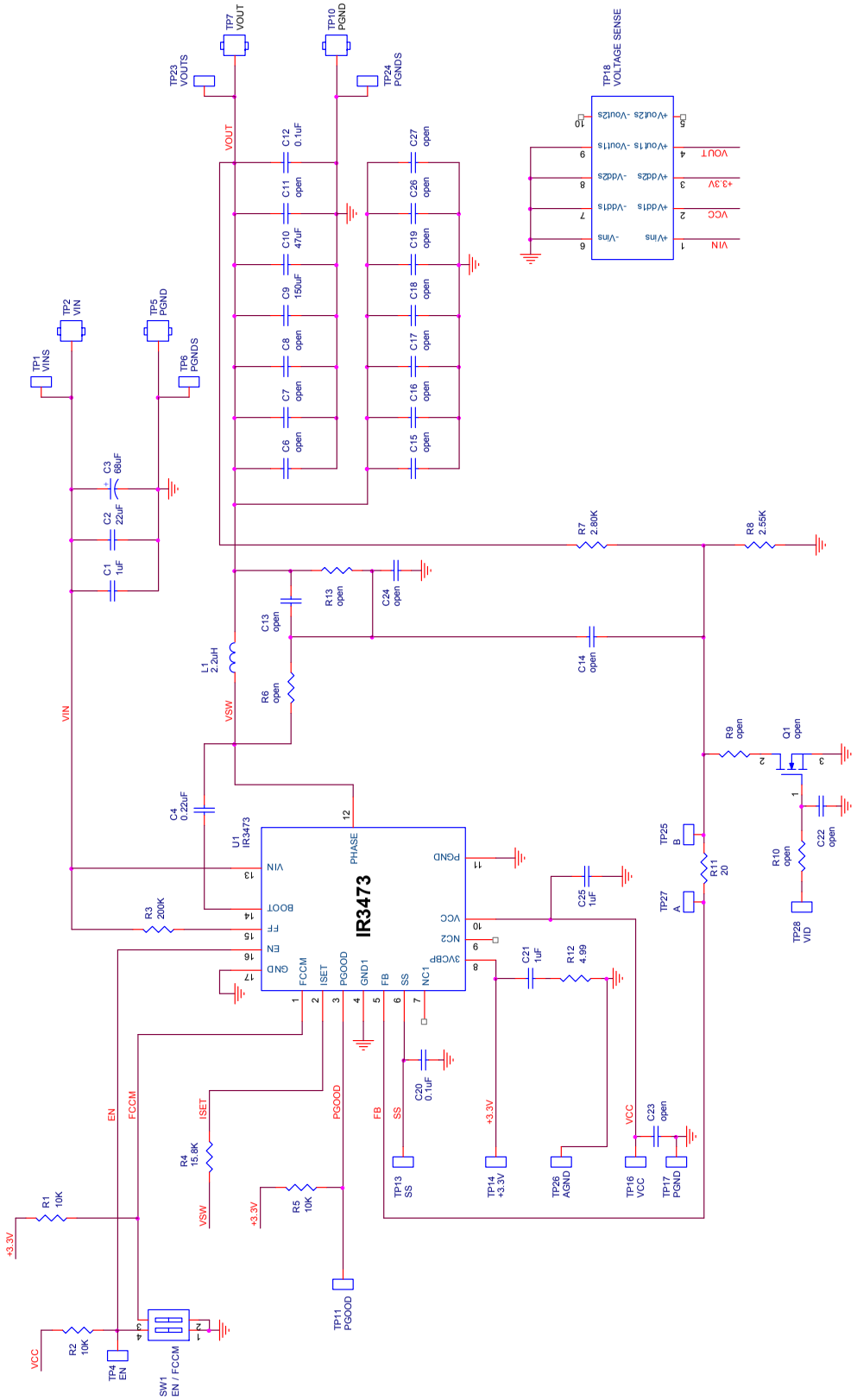

Fig. 8: Schematic of the IRDC3473 Evaluation Board

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Bill of Materials

QTY	REF DESIGNATOR	VALUE	DESCRIPTION	MANUFACTURER	PART NUMBER
3	C1, C21, C25	1.00uF	capacitor, X7R, 1.00uF, 25V, 0.1, 0603	Murata	GRM188R71E105KA12D
1	C10	47uF	capacitor, 47uF, 6.3V, 805	TDK	C2012X5R0J476M
2	C12, C20	0.100uF	capacitor, X7R, 0.100uF, 25V, 0.1, 603	TDK	C1608X7R1E104K
1	C2	22.0uF	capacitor, X5R, 22.0uF, 16V, 20%, 1206	Taiyo Yuden	EMK316BJ226ML-T
1	C3	68uF	capacitor, electrolytic, 68uF, 25V, 0.2, SMD	Panasonic	EEV-FK1E680P
1	C4	0.22uF	capacitor, X5R, 0.22uF, 10V, 0.1, 0603	TDK	C1608X5R1A224K
1	C9	150uF	capacitor, tantalum polymer, 150uF, 6.3V, 20%, 7343	Sanyo	6TPC150M
1	L1	2.2uH	inductor, ferrite, 2.2uH, 8.0A, 11.2mOhm, SMT	Cyntec	PCMB065T-2R2MS
1	R4	15.8K	resistor, thick film, 15.8K, 1/10W, 0.01, 603	KOA	RK73H1JLTD1582F
3	R1, R2, R5	10.0K	resistor, thick film, 10.0K, 1/10W, 0.01, 0603	KOA	RK73H1J1002F
1	R11	20	resistor, thick film, 20, 1/10W, 0.01, 603	KOA	RK73H1JLTD20R0F
1	R12	4.99	resistor, thick film, 4.99, 1/8W, 0.01, 603	KOA	RK73H1J4R99F
1	R3	200K	resistor, thick film, 200K, 1/10W, 0.01, 603	KOA	RK73H1JLTD2003F
1	R7	2.80K	resistor, thick film, 2.80K, 1/10W, 0.01, 603	KOA	RK73H1JLTD2801F
1	R8	2.55K	resistor, thick film, 2.55K, 1/10W, 0.01, 0603	KOA	RK73H1J2551F
1	SW1	SPST	switch, DIP, SPST, 2 position, SMT	C&K Components	SD02H0SK
1	U1	IR3473	4mm X 5mm QFN	IRF	IR3473MTRPBF

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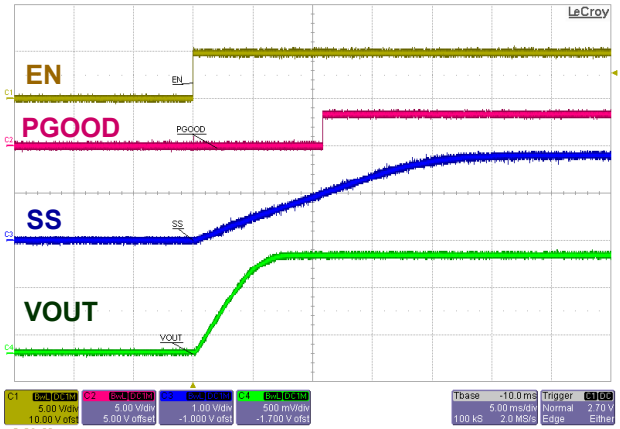
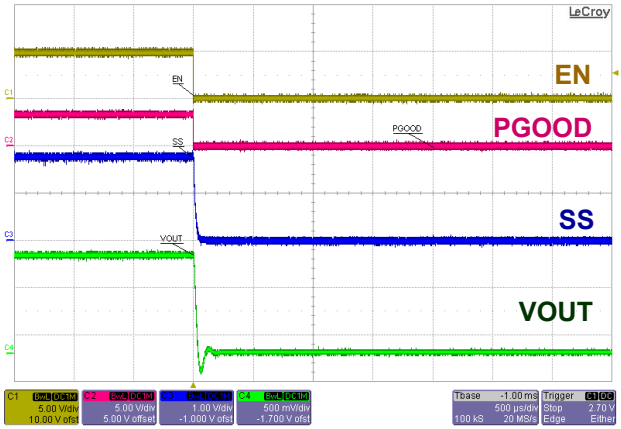
TYPICAL OPERATING WAVEFORMS

Tested with demoboard shown in Fig. 8, VIN = 12V, VCC = 5V, VOUT = 1.05V, Fs = 300kHz, T_A = 25°C, no airflow, unless otherwise specified



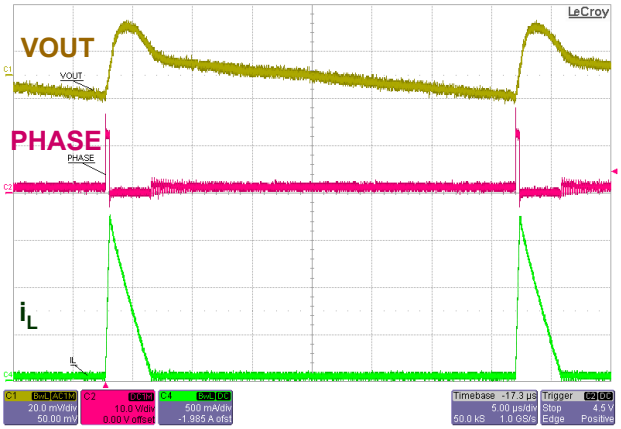
5V/div 5V/div 1V/div 500mV/div 5ms/div

Fig. 9: Startup



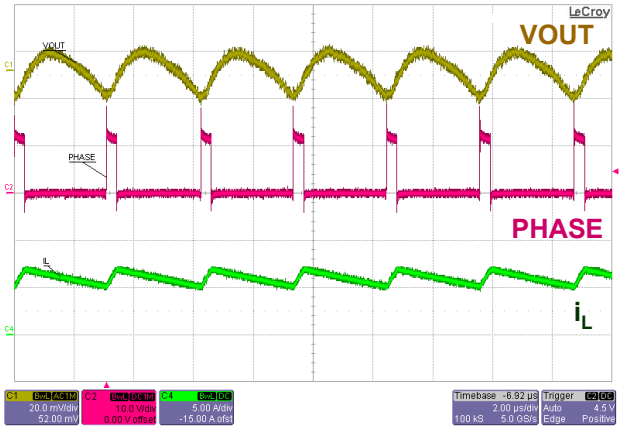
5V/div 5V/div 1V/div 500mV/div 500µs/div

Fig. 10: Shutdown



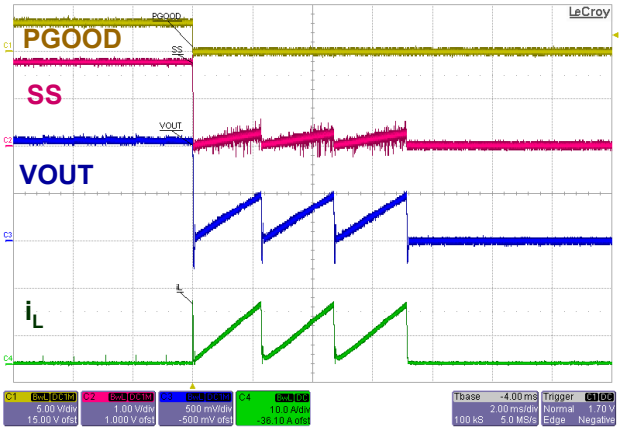
20mV/div 10V/div 500mA/div 5µs/div

Fig. 11: DCM (I_{OUT} = 0.1A)



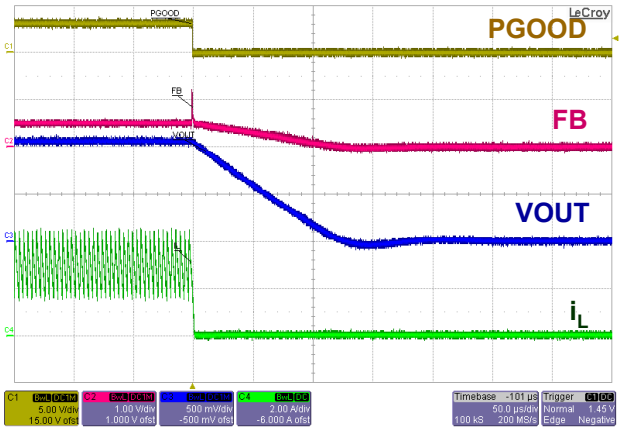
20mV/div 10V/div 5A/div 2µs/div

Fig. 12: CCM (I_{OUT} = 6A)



5V/div 1V/div 500mV/div 10A/div 2ms/div

Fig. 13: Over Current Protection (tested by shorting VOUT to PGND)



5V/div 1V/div 500mV/div 2A/div 50µs/div

Fig. 14: Over Voltage Protection (tested by shorting FB to VOUT)

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TYPICAL OPERATING WAVEFORMS

Tested with demoboard shown in Fig. 8, VIN = 12V, VCC = 5V, VOUT = 1.05V, Fs = 300kHz, T_A = 25°C, no airflow, unless otherwise specified

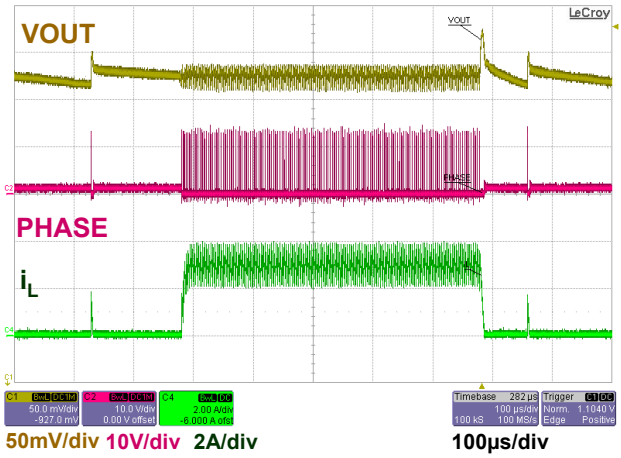

Fig. 15: Load Transient 0-3A

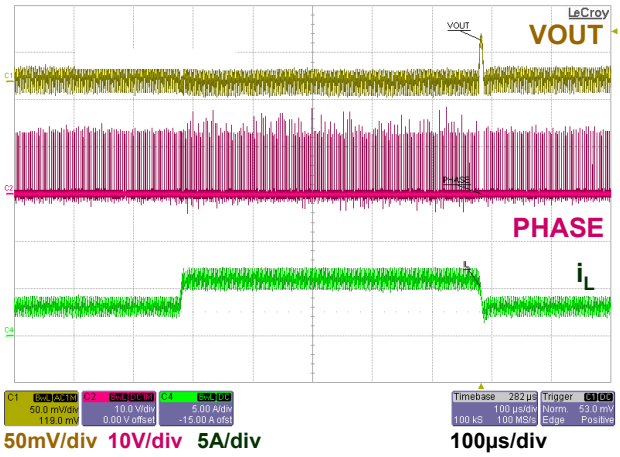

Fig. 16: Load Transient 3-6A

TYPICAL PERFORMANCE

VIN = 12V, VCC = 5V, VOUT = 1.05V, Fs = 300kHz, IOUT = 6A, T_A = 25°C, no airflow

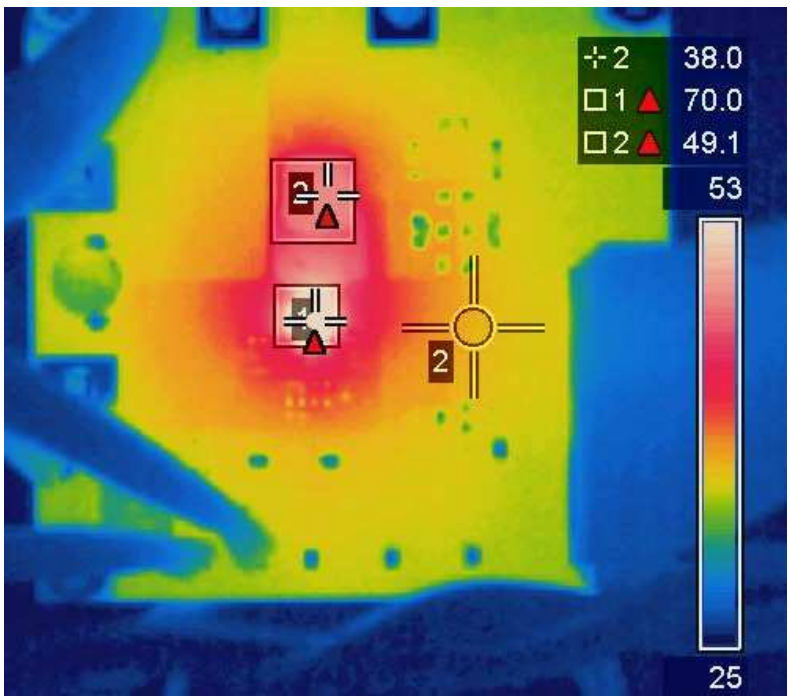

Fig. 17: Thermal Image (IR3473: 70°C, Inductor: 49°C, PCB: 38°C)

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TYPICAL OPERATING DATA

VIN = 12V, VCC = 5V, VOUT = 1.05V, Fs = 300kHz, IOUT = 0 ~ 6A, T_A = 25°C, no airflow, unless otherwise specified

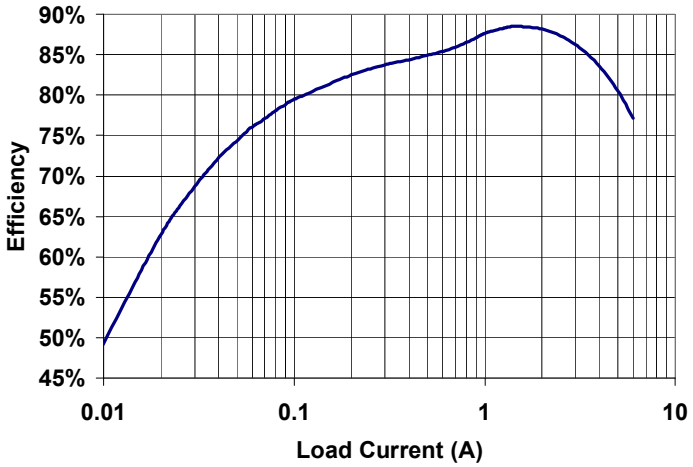

Fig. 18: Efficiency vs. Output Current

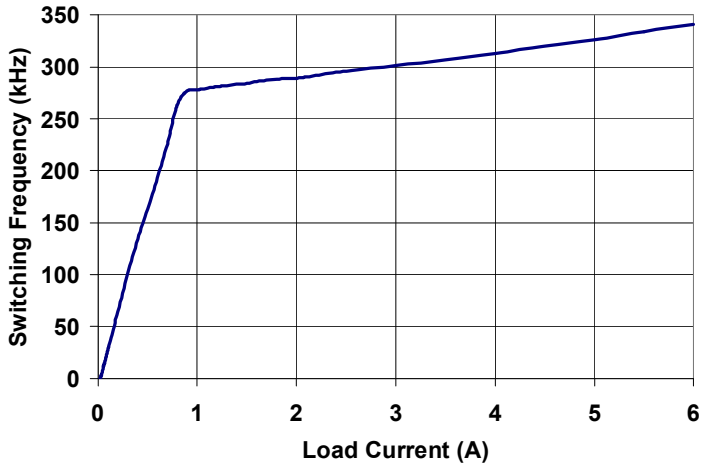

Fig. 19: Switching Frequency vs. Output Current

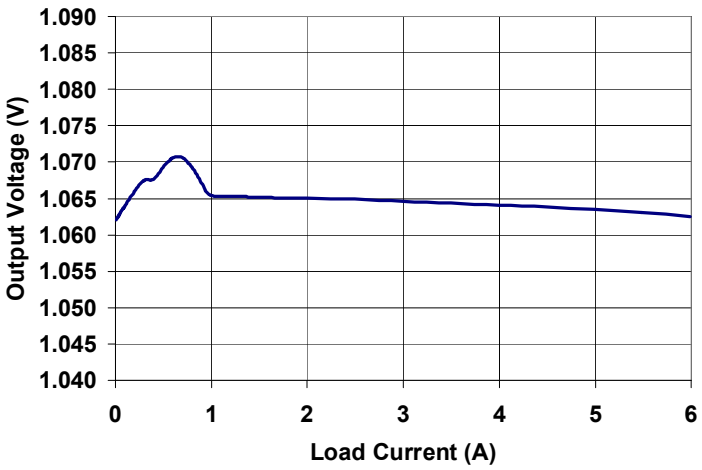

Fig. 20: Load Regulation

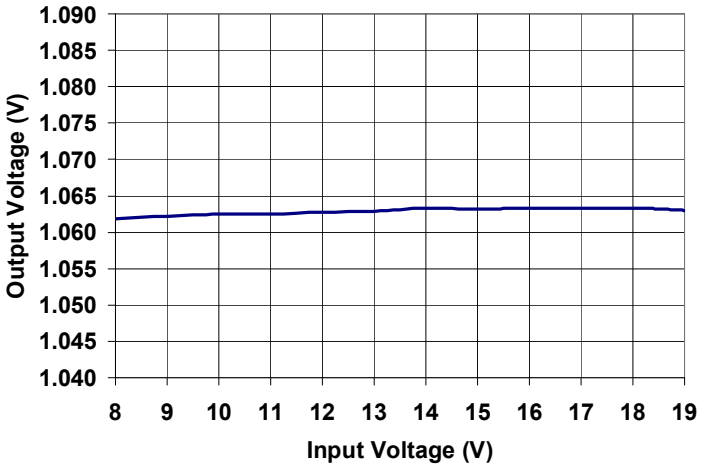

Fig. 21: Line Regulation at 6A Load

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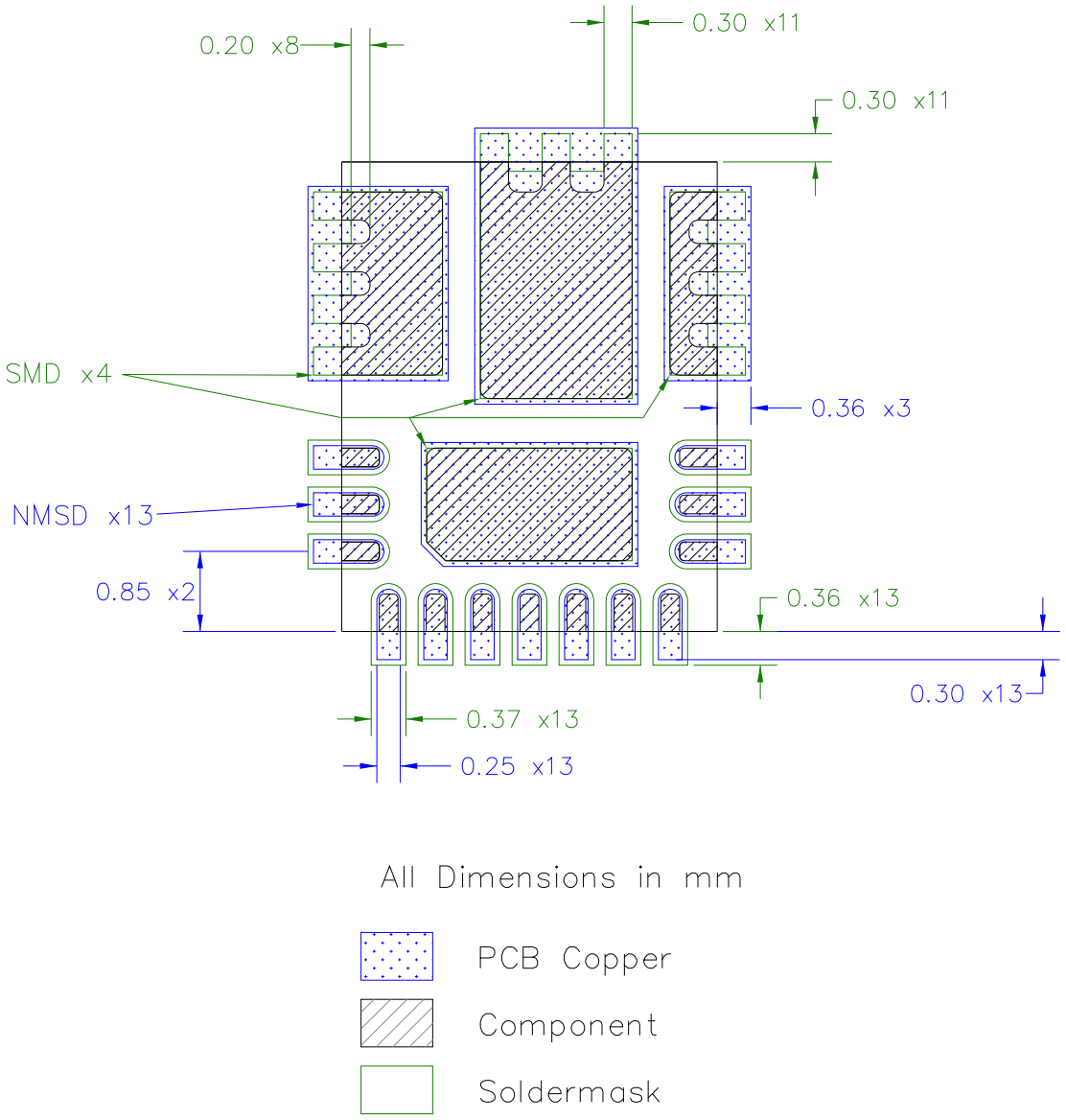
PCB Metal and Components Placement

Lead lands (the 13 IC pins) width should be equal to nominal part lead width. The minimum lead to lead spacing should be ≥ 0.2mm to minimize shorting.

Lead land length should be equal to maximum part lead length + 0.3 mm outboard extension. The outboard extension ensures a large toe fillet that can be easily inspected.

Pad lands (the 4 big pads) length and width should be equal to maximum part pad length and width. However, the minimum metal to metal spacing should be no less than 0.17mm for 2 oz. Copper, or no less than 0.1mm for 1 oz. Copper, or no less than 0.23mm for 3 oz. Copper.



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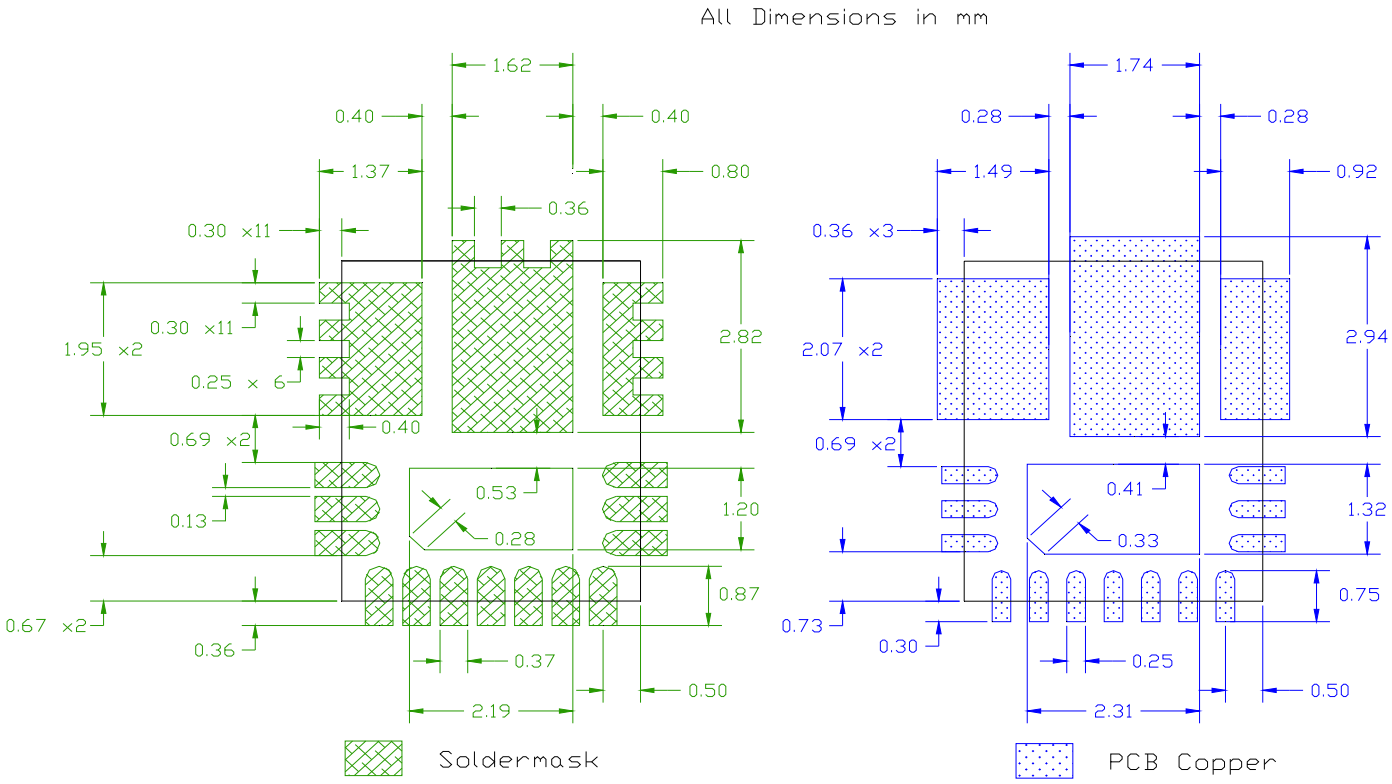
Solder Resist

It is recommended that the lead lands are Non Solder Mask Defined (NSMD). The solder resist should be pulled away from the metal lead lands by a minimum of 0.025mm to ensure NSMD pads.

The land pad should be Solder Mask Defined (SMD), with a minimum overlap of the solder resist onto the copper of 0.05mm to accommodate solder resist misalignment.

Ensure that the solder resist in between the lead lands and the pad land is ≥ 0.15mm due to the high aspect ratio of the solder resist strip separating the lead lands from the pad land.



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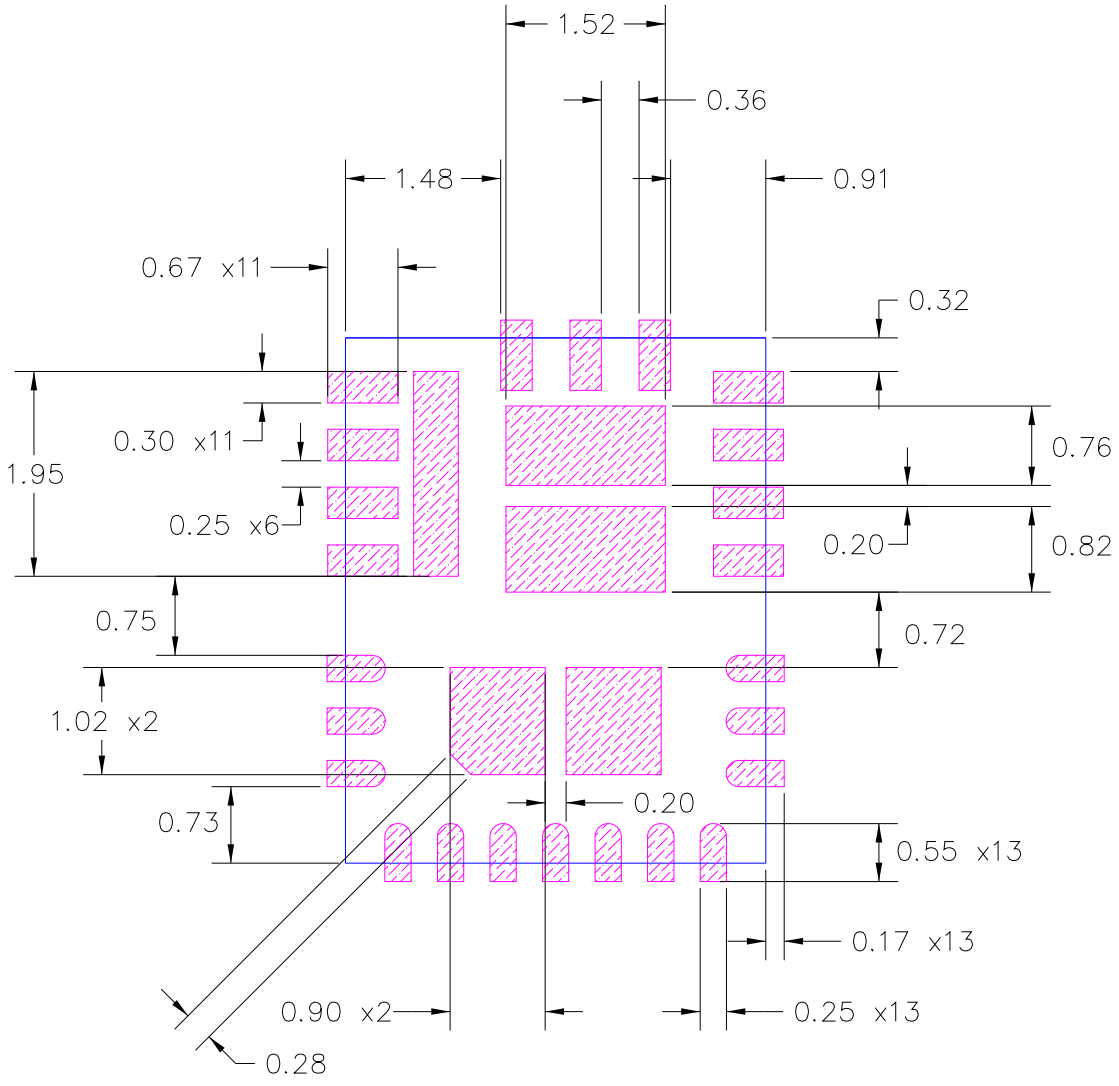
Stencil Design

The Stencil apertures for the lead lands should be approximately 80% of the area of the lead lads. Reducing the amount of solder deposited will minimize the occurrences of lead shorts. If too much solder is deposited on the center pad, the part will float and the lead lands will open.

The maximum length and width of the land pad stencil aperture should be equal to the solder resist opening minus an annular 0.2mm pull back in order to decrease the risk of shorting the center land to the lead lands when the part is pushed into the solder paste.



Stencil Aperture
All Dimensions in mm

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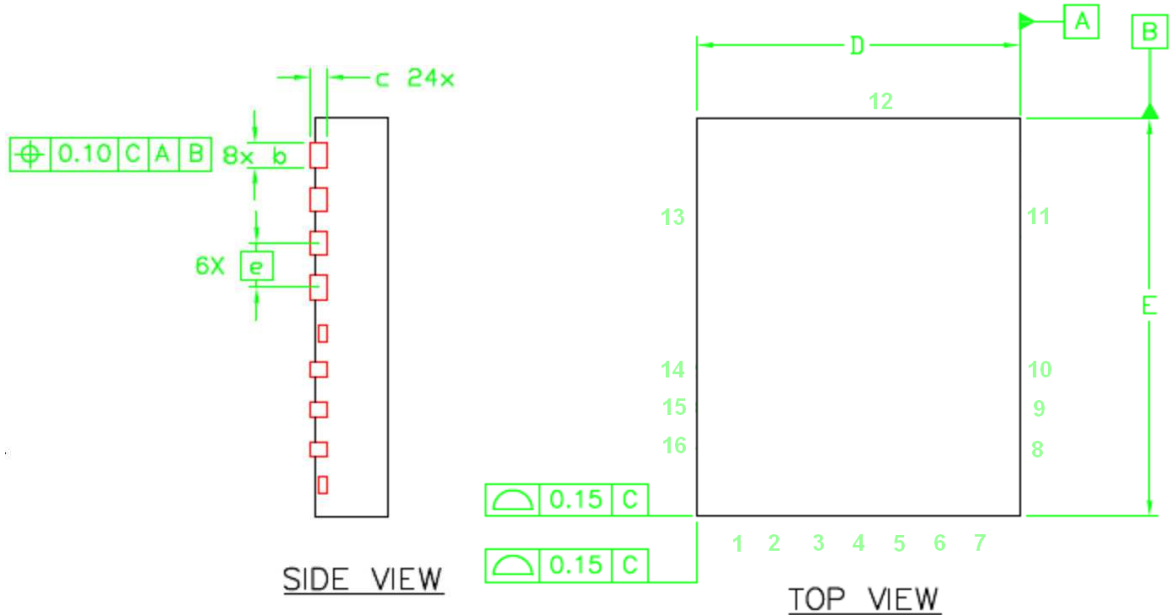
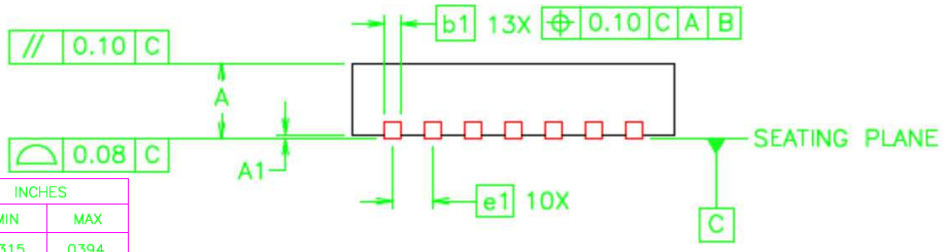
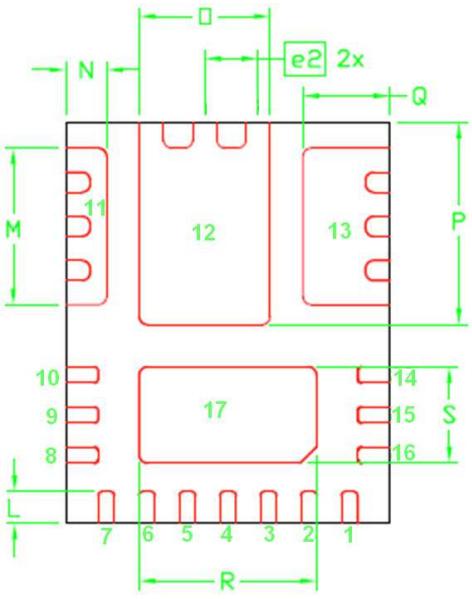




DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.800	1.000	.0315	.0394
A1	0.000	0.050	.0000	.0020
b	0.250	0.350	.0098	.0138
b1	0.150	0.250	.0059	.0098
c	0.203 REF.		.0080 REF.	
D	4.000 BASIC		.1575 BASIC	
E	5.000 BASIC		.1969 BASIC	
e	0.550 BASIC		.0217 BASIC	
e1	0.500 BASIC		.0197 BASIC	
e2	0.659 BASIC		.0259 BASIC	
L	0.350	0.450	.0138	.0177
M	1.900	2.000	.0748	.0787
N	0.453	0.553	.0178	.0218
O	1.567	1.667	.0617	.0656
P	2.470	2.570	.0972	.1012
Q	1.024	1.124	.0403	.0443
R	2.138	2.238	.0842	.0881
S	1.150	1.250	.0453	.0492



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